Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	pin with transfer and "118"/$.ccls	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 19:10
L2	0	epoxy and (drop or droplet) and "118"/$.ccls	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 19:17
L3	0	ciardella and "118"/$.ccls	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 19:17
L4	29	ciardella.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 19:43
L5	1951	circuit with board and (electrode with (protruding or protrude))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 19:43
L6	13	circuit with board and (electrode with (protruding or protrude)) and sealant with resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 19:43
L7	450	(118/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:02
L8	401	(118/679).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:02

L9	195	(118/680).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:02
L10	295	(118/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:02
L11	266	(118/669).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:02
L12	104	(118/677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:02
L13	561	(118/313).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:02
L14	823	(118/314).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:02
L15	870	(118/315).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:02
L16	78	(L7 L8 L9 L10 L11 L12 L13 L14 L15) and (sealant or resin or paste) and (semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 20:02
L17	1	("5932012").PN.	USPAT	OR	OFF	2005/09/18 20:02
L18	4	("5932012").URPN.	USPAT	OR	ON	2005/09/18 20:02

L19	2	("5415693" | "5437727").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 20:02
L20	113	(substrate near3 (heat or heater)) and (sealant near4 (resin or paste)) and (semiconductor) and control	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 20:02
L21	1	("5906682").PN.	USPAT	OR	OFF	2005/09/18 20:02